General De	ecrinti	on		Features							
	scripti			Features							
			PECL translator	Typical propagation delay of 300 ps							
operating from a s	ingle +5V s	supply.		 <100 ps between outputs Max I_{CC} of 30 mA Fairchild MSOP-8 package is a drop-in replacement to 							
			be terminated in								
			ut is being used. If can be left open								
The 100 series is t	emperature	e compensa	ated	Flow through pinout							
	omporatan	e componed		 Meets or exceeds JEDEC specification EIA/JESD78 latch-up test 	- 10						
				Moisture Sensitivity Level 1							
				ESD Performance:							
				Human Body Model > 2000V							
				Machine Model > 200V							
Ordering C	ode:										
		Product									
		Trouuci									
Order Number	Package	Code		Package Description							
Order Number	Package Number			Package Description							
Order Number	-	Code	8-Lead Small Outlir	Package Description e Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narro	w						
	Number	Code Top Mark KLT22									
00ELT22M 00ELT22M8 Preliminary)	Number M08A MA08D	Code Top Mark KLT22 KT22		e Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narro Il Outline Package (MSOP), JEDEC MO-187, 3.0mm Wide							
00ELT22M 00ELT22M8 Preliminary)	Number M08A MA08D in Tape and R	Code Top Mark KLT22 KT22 eel. Specify by	8-Lead Molded Sm	e Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narro Il Outline Package (MSOP), JEDEC MO-187, 3.0mm Wide							
00ELT22M 00ELT22M8 Preliminary) Devices also available i	Number M08A MA08D In Tape and R Diagr	Code Top Mark KLT22 KT22 eel. Specify by	8-Lead Molded Sm	e Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narro all Outline Package (MSOP), JEDEC MO-187, 3.0mm Wide to the ordering code.							
00ELT22M 00ELT22M8 Preliminary) Devices also available i Connectior Q0 –	Number M08A MA08D In Tape and R Diagr	Code Top Mark KLT22 KT22 eeel. Specify by cam	8-Lead Molded Sm appending suffix letter "X 3 - V _{CC}	e Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narro all Outline Package (MSOP), JEDEC MO-187, 3.0mm Wide to the ordering code. Logic Diagram							
00ELT22M 00ELT22M8 Preliminary) Devices also available i Connectior $Q_0 - \overline{Q}_0 $	Number M08A MA08D In Tape and R Diagr	Code Top Mark KLT22 KT22 eel. Specify by Cam	8-Lead Molded Sm appending suffix letter "X	e Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narro all Outline Package (MSOP), JEDEC MO-187, 3.0mm Wide to the ordering code.							
00ELT22M 00ELT22M8 Preliminary) Devices also available i Connectior Q0 – Q0 – Q1 –	Number M08A MA08D In Tape and R Diagr	Code Top Mark KLT22 KT22 eel. Specify by Cam	8-Lead Molded Sm appending suffix letter "X VCC D0 D1	e Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narro all Outline Package (MSOP), JEDEC MO-187, 3.0mm Wide to the ordering code. Logic Diagram							
00ELT22M 00ELT22M8 Preliminary) Devices also available i Connectior $Q_0 - \overline{Q}_0 $	Number M08A MA08D In Tape and R Diagr	Code Top Mark KLT22 KT22 eel. Specify by Cam	8-Lead Molded Sm appending suffix letter "X	e Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narro all Outline Package (MSOP), JEDEC MO-187, 3.0mm Wide to the ordering code. Logic Diagram $Q_0 \longrightarrow D_0$							
00ELT22M 00ELT22M8 Preliminary) Devices also available i Connectior Q0 – Q0 – Q1 –	Number M08A MA08D In Tape and R Diagr 1 2 3 4	Code Top Mark KLT22 KT22 eel. Specify by Tam	8-Lead Molded Sm appending suffix letter "X VCC D0 D1	e Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narro all Outline Package (MSOP), JEDEC MO-187, 3.0mm Wide to the ordering code. Logic Diagram Q_0 $\overline{Q_0}$ D_0 Q_1							
00ELT22M 00ELT22M8 Preliminary) Devices also available i Connectior Q0 – Q0 – Q1 –	Number M08A MA08D In Tape and R Diagr 1 2 3 4	Code Top Mark KLT22 KT22 eel. Specify by Cam	8-Lead Molded Sm appending suffix letter "X VCC D0 D1	e Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narro all Outline Package (MSOP), JEDEC MO-187, 3.0mm Wide to the ordering code. Logic Diagram $Q_0 \longrightarrow D_0$							
00ELT22M 00ELT22M8 Preliminary) Devices also available i Connectior Q0 – Q0 – Q1 –	Number M08A MA08D in Tape and R Diagr 1 2 3 4 Top	Code Top Mark KLT22 KT22 eel. Specify by Tam	8-Lead Molded Sm appending suffix letter "X VCC D0 D1	e Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narro all Outline Package (MSOP), JEDEC MO-187, 3.0mm Wide to the ordering code. Logic Diagram Q_0 $\overline{Q_0}$ D_0 Q_1 D_1							
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00ELT22M 00ELT22M8 Preliminary) Devices also available i Connection Q0 - Q0 - Q1 -	Number M08A MA08D in Tape and R Diagr Diagr 1 2 3 4 Top Dtions	Code Top Mark KLT22 KT22 eel. Specify by cam cam c t View Des	8-Lead Molded Sm appending suffix letter "X - V _{CC} - D ₀ - D ₁ - GND - GND	e Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narro all Outline Package (MSOP), JEDEC MO-187, 3.0mm Wide to the ordering code. Logic Diagram Q_0 $\overline{Q_0}$ D_0 Q_1 D_1							
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00ELT22M 00ELT22M8 Preliminary) Devices also available i Connection Q0 - Q0 - Q1 -	Number M08A MA08D In Tape and R Diagr Diagr 1 2 3 4 Top Diagr	Code Top Mark KLT22 KT22 eeel. Specify by cam a b c t view PECL Diffe	8-Lead Molded Sm appending suffix letter "X V _{CC} D ₀ D ₁ GND scription erential Outputs	e Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narro all Outline Package (MSOP), JEDEC MO-187, 3.0mm Wide to the ordering code. Logic Diagram Q_0 $\overline{Q_0}$ D_0 Q_1 D_1							

SEMICONDUCTOR

100ELT22 5V _ . -..... . .

Gen

FAIRCHILD

January 2003

Revised January 2003

100ELT22 5V Dual TTL to Differential PECL Translator

Orde

		Product	
Order Number	Package	Code	Package Description
	Number	Top Mark	
100ELT22M	M08A	KLT22	8-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
100ELT22M8 (Preliminary)	MA08D	KT22	8-Lead Molded Small Outline Package (MSOP), JEDEC MO-187, 3.0mm Wide

Con

Pin

Pin Name	Description
Q_n, \overline{Q}_n	PECL Differential Outputs
D ₀ , D ₁	TTL Inputs
V _{CC}	Positive Supply
GND	Ground



Absolute Maximum Ratings(Note 1)

Supply Voltage (V _{CC}) Input Voltage (V _I) V _I \leq V _{CC}	0.0V to +7.0V 0.0V to + 7.0V
DC Output Current (I _{OUT})	
Continuous	50 mA
Surge	100 mA
Storage Temperature (T_{STG})	$-65^{\circ}C$ to $+ 150^{\circ}C$

Recommended Operating Conditions

Power Supply Operating TTL Input Voltage Free Air Operating Temperature (T_A)

 $V_{CC} = 4.2V \text{ to } 5.5V$ 0.0V to V_{CC} $-40^{\circ}\text{C to } +85^{\circ}\text{C}$

Note 1: The "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the absolute maximum rating. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

PECL DC Electrical Characteristics $V_{CC} = 5.0V$; GND = 0.0V (Note 2)

Symbol	Parameter	-40°C			25°C			85°C			Units
Symbol	Falameter	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Units
I _{CC}	Power Supply Current			30			30			30	mA
V _{OH}	Output HIGH Voltage (Note 3)	3915	3995	4120	3975	4045	4120	3975	4050	4120	mV
V _{OL}	Output LOW Voltage (Note 3)	3170	3305	3445	3190	3295	3380	3190	3295	3380	mV
Note 2: Ou	Note 2: Output parameters vary 1 to 1 with V _{CC} . V _{CC} can vary +0.5V/-0.8V.										

Note 3: Outputs are terminated through a 50Ω Resistor to V_{CC} – 2.0V.

Note: Devices are designed to meet the DC specifications after thermal equilibrium has been established. Circuit is tested with air flow greater than 500LFPM maintained.

TTL DC Electrical Characteristics $V_{CC} = 5.0V$; GND = 0.0V (Note 4); $T_A = -40^{\circ}C$ to $+85^{\circ}C$

Symbol	Parameter	Min	Тур	Max	Units	Condition
I _{IH}	Input HIGH Current			20		V _{IN} = 2.7V
				100	μA	$V_{IN} = V_{CC}$
IIL	Input LOW Current			-200	μA	V _{IN} = 0.5V
V _{IK}	Clamp Diode Voltage			-1.2	V	I _{IN} = -18 mA
V _{IH}	Input HIGH Voltage	2.0			V	
V _{IL}	Input LOW Voltage			0.8	V	

Note 4: V_{CC} can vary +0.5V/-0.8V.

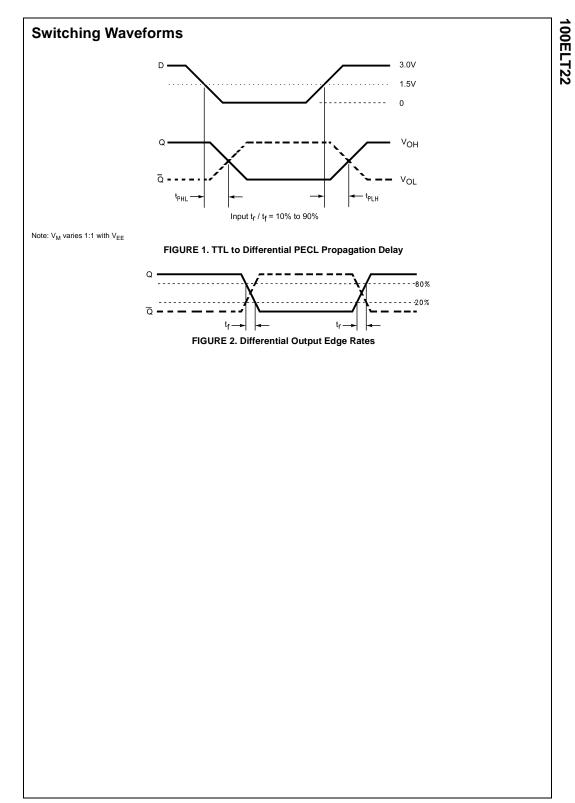
AC Electrical Characteristics $V_{CC} = 5.0V$; GND = 0.0V (Note 5)

Symbol	Parameter	-40°C			25°C			85°C			Units	Figure
	Falameter	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Units	Number
f _{MAX}	Maximum Input Frequency		TBD			TBD			TBD		MHz	
t _{JITTER}	Cycle-to-Cycle Jitter		TBD			TBD			TBD		ps	
t _{PLH} , t _{PHL}	Propagation Delay to Output (Note 6)	100		600	100		600	100		600	ps	Figure 1
t _r , t _f	Output Rise Time/Fall Times (20% to 80%)	200		500	200		500	200		500	ns	Figure 2
t _{skpp}	Part to Part Skew			500			500			500	ps	
t _{skew}	Within Device Skew (Note 7)			100			100			100	ps	

Note 5: V_{CC} can vary +0.5V/-0.8V.

Note 6: Specifications for standard TTL input signal (see Figure 1).

Note 7: Within-device skew is defined as identical transitions on similar paths through a device.



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